

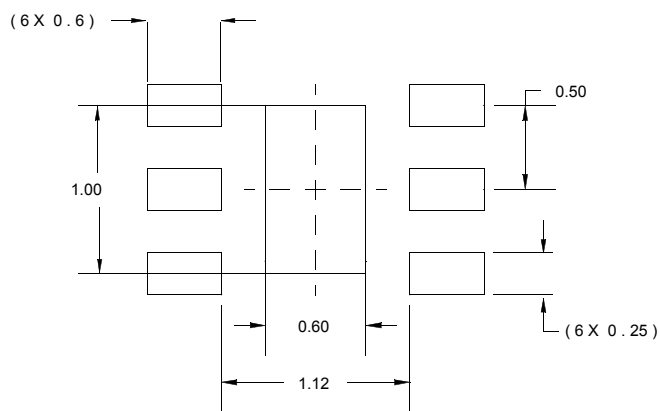
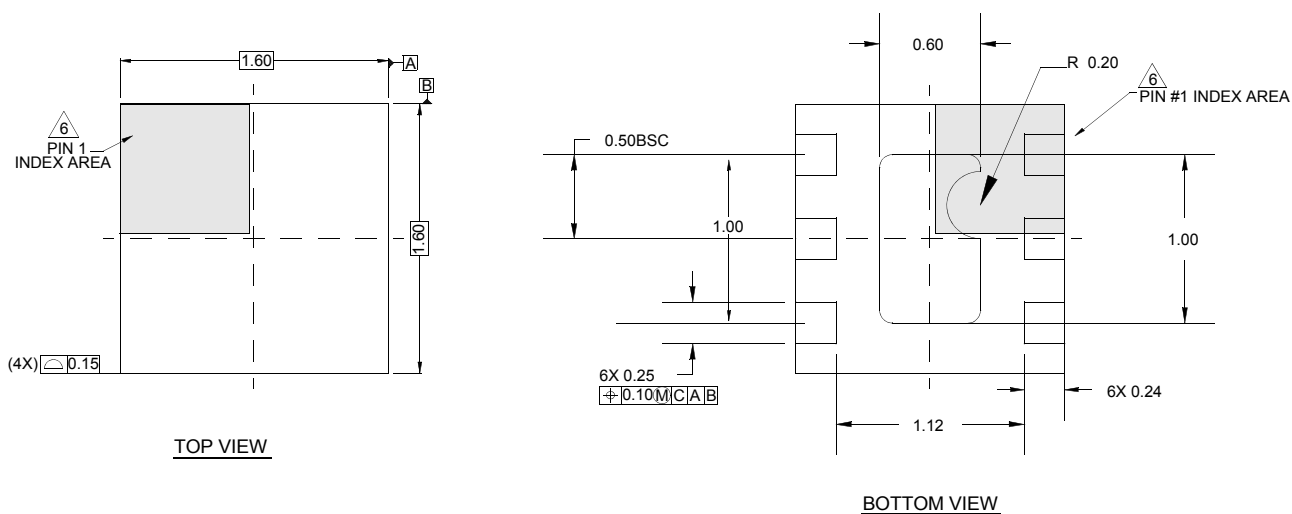
Plastic Packages for Integrated Circuits

Package Outline Drawing

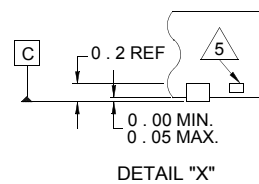
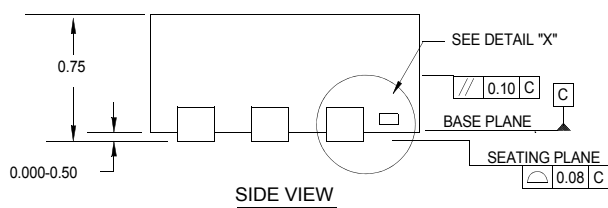
L6.1.6x1.6B

6 LEAD THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE (TDFN)

Rev 2, 05/15



TYPICAL RECOMMENDED LAND PATTERN



NOTES:

1. Dimensions are in millimeters.
Dimensions in () for Reference Only.
2. Dimensioning and tolerancing conform to AMSEY14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Dimension b applies to the metallized terminal and is measured between 0.20mm and 0.30mm from the terminal tip.

- 5. Tiebar shown (if present) is a non-functional feature and may be located on any of the 4 sides (or ends).
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.